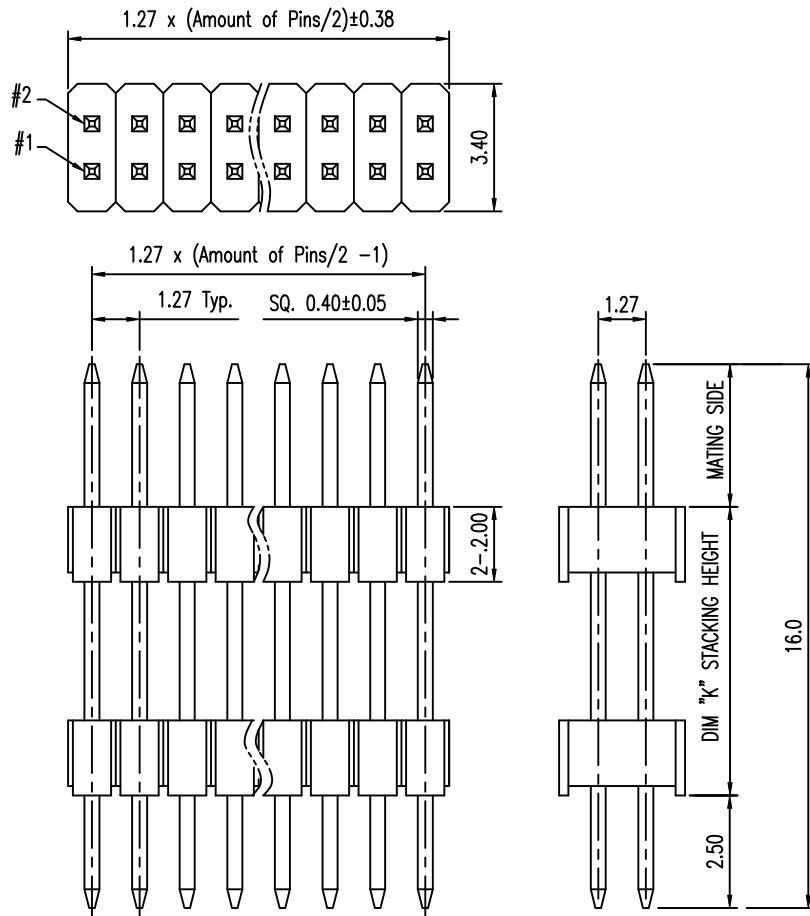




NOTE:

- MATERIAL:
HOUSING: HIGH TEMP THERMAL PLASTIC, UL94-V0
TERMINAL: COPPER ALLOY
- FINISH:
TERMINAL: GOLD AT CONTACT,
G/F OVER 1UM(40U") MIN NI OVER ALL
- SPEC.:
PRODUCT SPEC: GS-12-629
PACKING SPEC: GS-14-1517
- THE HSG. WILL WITHSTAND EXPOSURE TO 260C
PEAK TEMP. FOR 10 SEC. IN A WAVE SOLDER APPLICATION.
- MATING SIDE LENGTH: 2.5MM MIN.
- PRODUCT NUMBERING:
200218 1 1 - XXX XX X X LF

LEAD FREE

PLATING:

1: G/F ALL OVER

4: 0.25UM(10U") GOLD AT CONTACT

8: 0.76UM(30U") GOLD AT CONTACT

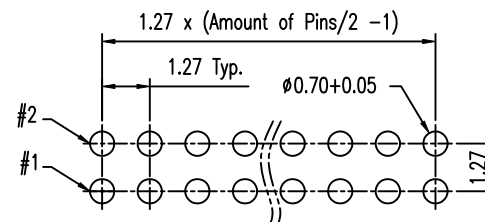
PACKING

T: TUBE

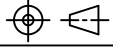
PIN COUNT

04, 06, 08, ..., 98, A0
(EVERY EVEN PIN)

STACK HEIGHT "K"
EXAMPLE: 045=4.5MM
IN 0.5MM INCREMENT



Recommended P.C.B. Layout (TH)
Layout Tolerance = ± 0.05 mm

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	 www.fciconnect.com		
ltr	ecn no	dr	date	linear	.X ± 0.38				
A	T10-0065	S.LIN	10'-5-20		.XX ± 0.25	projection	title 1.27X1.27MM BTB STACK HD VT, TH		
				angles	.XXX ± 0.15				
				dr	STERLING LIN	10'-5-20	MM	product family 585	
				enrg	STERLING LIN	10'-5-20		code size dwg no	
				chr	STERLING LIN	10'-5-20	scale	A4	
				appd	GARY HSIEH	10'-5-20		20021814	
sheet index	revision sheet	A	1						